

## WEST Search History

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DATE: Thursday, April 22, 2004

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		<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>	
<input type="checkbox"/>	L7	l3 and (gas guard)	1
<input type="checkbox"/>	L6	l3 and (gas injection tube)	1
<input type="checkbox"/>	L5	L3 and (gas spraying)	9
<input type="checkbox"/>	L4	L3 and (forming water layer)	1
<input type="checkbox"/>	L3	L1 and (water supply )	1488
<input type="checkbox"/>	L2	L1 and (water supply means)	0
<input type="checkbox"/>	L1	cleaning apparatus	28443

END OF SEARCH HISTORY

L Number	Hits	Search Text	DB	Time stamp
1	2820	((134/182,183,148,153,902).CCLS.)	USPAT; US-PGPUB	2004/04/22 11:49
2	966	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)	USPAT; US-PGPUB	2004/04/22 11:51
3	953	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)	USPAT; US-PGPUB	2004/04/22 11:52
4	847	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)	USPAT; US-PGPUB	2004/04/22 11:53
5	806	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)	USPAT; US-PGPUB	2004/04/22 11:54
6	538	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber	USPAT; US-PGPUB	2004/04/22 11:54
7	477	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)	USPAT; US-PGPUB	2004/04/22 11:55
8	351	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)	USPAT; US-PGPUB	2004/04/22 11:55
11	0	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and (frustoconical)) and holes) and (megasonic transducer)	USPAT; US-PGPUB	2004/04/22 11:59
10	2	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and (frustoconical)) and holes	USPAT; US-PGPUB	2004/04/22 11:59
9	7	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and (frustoconical)	USPAT; US-PGPUB	2004/04/22 12:17
12	81	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and megasonic	USPAT; US-PGPUB	2004/04/22 12:18

13.	81	(((((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer) and chamber) and (single type)) and (x-y drive mechanism)) and megasonic) and (cleaning gas)	USPAT; US-PGPUB	2004/04/22 12:18
-	0	(136/6).CCLS.	USPAT; US-PGPUB	2004/04/22 11:48
-	1132	(134/6).CCLS.	USPAT; US-PGPUB	2003/10/28 13:36
-	266	134/1.ccls. and (electrostatic charge)	USPAT; US-PGPUB	2003/10/28 13:38
-	191	(134/1.ccls. and (electrostatic charge)) and (semiconductor processing tool)	USPAT; US-PGPUB	2003/10/28 13:39
-	105	(156/345.35).CCLS.	USPAT; US-PGPUB	2004/03/29 11:20
-	0	("llandopticsormirrororrutheniumorcollector	USPAT; US-PGPUB	2004/03/29 11:22
-	15	((156/345.35).CCLS.) and (optics or mirror or collectors or ruthenium)	USPAT; US-PGPUB	2004/03/29 11:23
-	105	(134/1.1 and etchant) and energy	USPAT; US-PGPUB	2004/03/29 11:55
-	5	((134/1.1 and etchant) and energy) and light) and mirror	USPAT; US-PGPUB	2004/03/29 11:43
-	4	((134/1.1 and etchant) and energy) and light) and optics	USPAT; US-PGPUB	2004/03/29 11:43
-	163	134/1.1 and etchant	USPAT; US-PGPUB	2004/03/29 11:51
-	1351	134/1.3	USPAT; US-PGPUB	2004/03/29 11:52
-	46	((134/1.1 and etchant) and energy) and light	USPAT; US-PGPUB	2004/03/29 11:56
-	1663	134/21	USPAT; US-PGPUB	2004/03/29 11:56
-	39	134/21 and ionizing	USPAT; US-PGPUB	2004/03/29 14:18
-	619653	lithograph chamber	USPAT; US-PGPUB	2004/03/29 14:19
-	646813	lithography chamber	USPAT; US-PGPUB	2004/03/29 14:19
-	377610	(lithography chamber) and (optical component)	USPAT; US-PGPUB	2004/03/29 14:20
-	44457	((lithography chamber) and (optical component)) and etching	USPAT; US-PGPUB	2004/03/29 14:21
-	43483	((lithography chamber) and (optical component)) and etching) and (first chamber)	USPAT; US-PGPUB	2004/03/29 14:21
-	8255	((lithography chamber) and (optical component)) and etching) and (first chamber)) and mirror	USPAT; US-PGPUB	2004/03/29 14:22
-	8054	((lithography chamber) and (optical component)) and etching) and (first chamber)) and mirror) and (first etchant)	USPAT; US-PGPUB	2004/03/29 14:23
-	7703	((lithography chamber) and (optical component)) and etching) and (first chamber)) and mirror) and (first etchant)) and (light source)	USPAT; US-PGPUB	2004/03/29 14:23
-	1040	((lithography chamber) and (optical component)) and etching) and (first chamber)) and mirror) and (first etchant)) and (light source)) and ioniz\$	USPAT; US-PGPUB	2004/03/29 14:24
-	317	((lithography chamber) and (optical component)) and etching) and (first chamber)) and mirror) and (first etchant)) and (light source)) and ioniz\$) and (incidence collectors)	USPAT; US-PGPUB	2004/03/29 14:24

-	185	(((((((lithography chamber) and (optical component)) and etching) and (first chamber)) and mirror) and (first etchant)) and (light source)) and ioniz\$ and (incidence collectors)) and cleaning	USPAT; US-PGPUB	2004/03/29 14:25
-	9	(((((((lithography chamber) and (optical component)) and etching) and (first chamber)) and mirror) and (first etchant)) and (light source)) and ioniz\$ and (incidence collectors)) and cleaning) and 156/\$.ccls.	USPAT; US-PGPUB	2004/03/29 14:26

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1	2820	(134/182,183,148,153,902).CCLS.	USPAT; US-PGPUB	2004/04/22 11:49
2	966	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)	USPAT; US-PGPUB	2004/04/22 11:51
3	953	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)	USPAT; US-PGPUB	2004/04/22 11:52
4	847	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)	USPAT; US-PGPUB	2004/04/22 11:53
5	806	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)	USPAT; US-PGPUB	2004/04/22 11:54
6	538	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber	USPAT; US-PGPUB	2004/04/22 11:54
7	477	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)	USPAT; US-PGPUB	2004/04/22 11:55
8	351	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)	USPAT; US-PGPUB	2004/04/22 11:55
11	0	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and (frustoconical)) and holes) and (megasonic transducer)	USPAT; US-PGPUB	2004/04/22 11:59
10	2	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and (frustoconical)) and holes	USPAT; US-PGPUB	2004/04/22 11:59
9	7	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and (frustoconical)	USPAT; US-PGPUB	2004/04/22 12:17
12	81	((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and megasonic	USPAT; US-PGPUB	2004/04/22 12:18

13	81	(((((134/182,183,148,153,902).CCLS.) and (cleaning apparatus) and (water supply\$) and (gas spray\$) and (gas guard)) and (gas injection tube)) and (rotary wafer chuck)) and (water layer)) and chamber) and (single type)) and (x-y drive mechanism)) and megasonic) and (cleaning gas)	USPAT; US-PGPUB	2004/04/22 13:52
15	0	("14andgasspraying").PN.	USPAT; US-PGPUB	2004/04/22 13:54
16	0	("14andgasspraying").PN.	USPAT; US-PGPUB	2004/04/22 13:54
14	1532	(134/902).CCLS.	USPAT; US-PGPUB	2004/04/22 14:36
17	753	(134/153).CCLS.	USPAT; US-PGPUB	2004/04/22 14:37